

# APT1608LSECK/J3-PRV

1.6 x 0.8 mm SMD Chip LED Lamp



# **DESCRIPTIONS**

- The Hyper Red device is based on light emitting diode chip made from AlGaInP
- · Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

## **FEATURES**

- 1.6 mm x 0.8 mm SMD LED, 0.75 mm thickness
- Low power consumption
- · Wide viewing angle
- · Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- · RoHS compliant

## **APPLICATIONS**

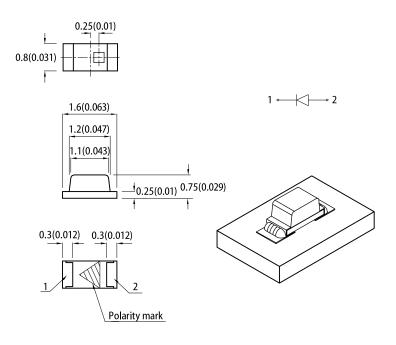
- Backlight
- · Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

# **ATTENTION**

Observe precautions for handling electrostatic discharge sensitive devices

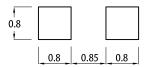


# **PACKAGE DIMENSIONS**



# RECOMMENDED SOLDERING PATTERN

(units: mm; tolerance:  $\pm$  0.1)



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.1(0.004") unless otherwise noted.
  3. The specifications, characteristics and technical data described in the datasheet are subject to
- change without prior notice.

  4. The device has a single mounting surface. The device must be mounted according to the specifications.

### **SELECTION GUIDE**

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 2mA [2]		Viewing Angle [1]	
			Min.	Тур.	201/2	
APT1608LSECK/J3-PRV	■ Hyper Red (AlGalnP)	Water Clear	50	100	120°	
			*20	*40	120	

1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous flux: +/-15%.

\* Luminous intensity value is traceable to CIE127-2007 standards.





# ELECTRICAL / OPTICAL CHARACTERISTICS at T<sub>A</sub>=25°C

Parameter	Symphol	Fusition Color	Value			Unit
Parameter	Symbol	Emitting Color	Min.	Тур.	Тур. Мах.	UIIIL
Wavelength at Peak Emission I <sub>F</sub> = 2mA	$\lambda_{peak}$	Hyper Red	-	640	-	nm
Dominant Wavelength I <sub>F</sub> = 2mA	λ <sub>dom</sub> <sup>[1]</sup>	Hyper Red	-	625	-	nm
Spectral Bandwidth at 50% $\Phi$ REL MAX I <sub>F</sub> = 2mA	Δλ	Hyper Red	-	20	-	nm
Capacitance	С	Hyper Red	-	27	-	pF
Forward Voltage I <sub>F</sub> = 2mA	V <sub>F</sub> <sup>[2]</sup>	Hyper Red	1.5	1.8	2.1	V
Reverse Current (V <sub>R</sub> = 5V)	I <sub>R</sub>	Hyper Red	-	-	10	μА
Temperature Coefficient of $\lambda_{peak}$ $I_F=2mA,$ -10° $C \leq T \leq 85^{\circ}C$	$TC_{\lambda peak}$	Hyper Red	-	0.13	-	nm/°C
Temperature Coefficient of $\lambda_{dom}$ $I_F=2mA,$ -10° $C \leq T \leq 85^{\circ}C$	$TC_{\lambdadom}$	Hyper Red	-	0.06	-	nm/°C
Temperature Coefficient of $V_F$ $I_F$ = 2mA, -10°C $\leq$ T $\leq$ 85°C	TC <sub>V</sub>	Hyper Red	-	-2.0	-	mV/°C

### Notes:

# ABSOLUTE MAXIMUM RATINGS at $T_A=25$ °C

Parameter	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	84	mW
Reverse Voltage	$V_{R}$	5	V
Junction Temperature	T <sub>j</sub>	115	°C
Operating Temperature	T <sub>op</sub>	-40 to +85	°C
Storage Temperature	T <sub>stg</sub>	-40 to +85	°C
DC Forward Current	I <sub>F</sub>	30	mA
Peak Forward Current	I <sub>FM</sub> <sup>[1]</sup>	150	mA
Electrostatic Discharge Threshold (HBM)	-	3000	V
Thermal Resistance (Junction / Ambient)	R <sub>th JA</sub> <sup>[2]</sup>	400	°C/W
Thermal Resistance (Junction / Solder point)	R <sub>th JS</sub> <sup>[2]</sup>	285	°C/W

The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd: ±1nm.)
 Forward voltage: ±0.1V.
 Wavelength value is traceable to CIE127-2007 standards.
 Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

To Duty Cycle, 0.1ms Pulse Width.

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

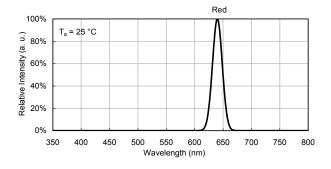
2. R<sub>th JA</sub>, R<sub>th JS</sub> Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).

3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

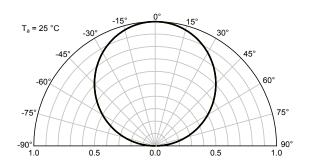


## **TECHNICAL DATA**

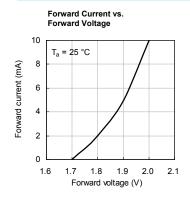
### **RELATIVE INTENSITY vs. WAVELENGTH**

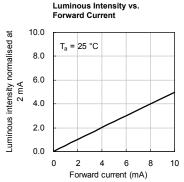


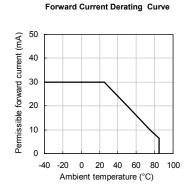
# **SPATIAL DISTRIBUTION**

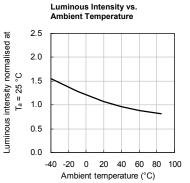


# **HYPER RED**

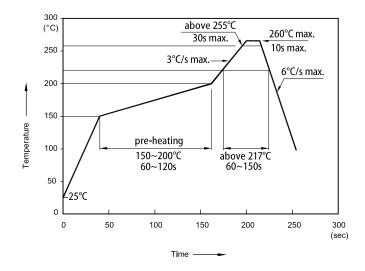






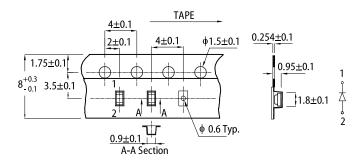


# **REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS**

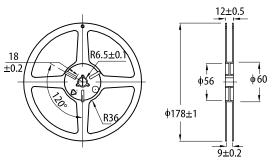


- Don't cause stress to the LEDs while it is exposed to high temperature.
- The maximum number of reflow soldering passes is 2 times.
   Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

### TAPE SPECIFICATIONS (units: mm)

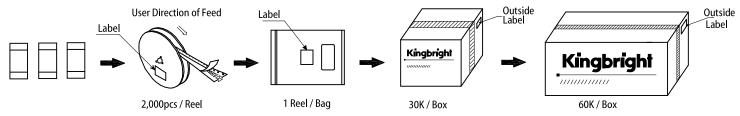


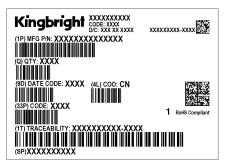
# **REEL DIMENSION** (units: mm)





## **PACKING & LABEL SPECIFICATIONS**





PRECAUTIONARY NOTES

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.

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